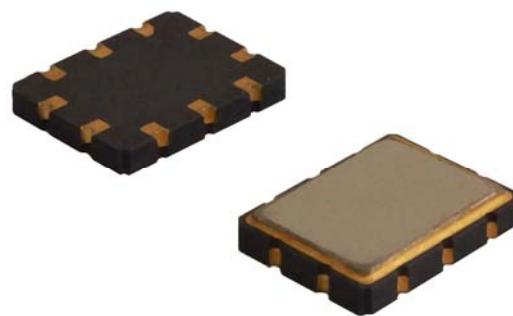


Application

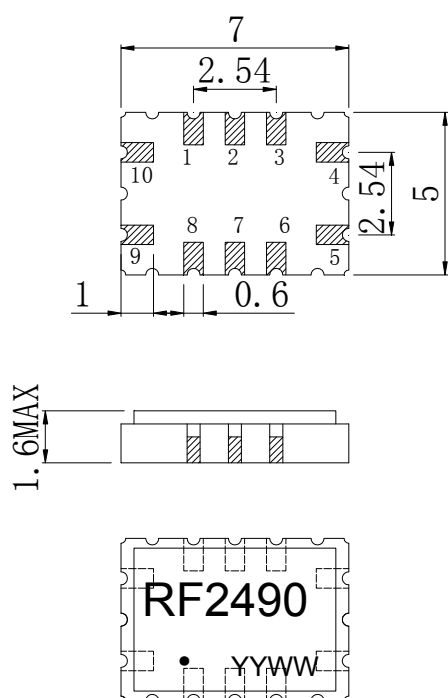
- Low-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Usable passband 38.0 MHz

Features

- Ceramic Package for Surface Mounted Technology (SMT)
- RoHS compatible
- Package size 7.00x5.00x1.60mm³
- Package Code QCC12C
- Electrostatic Sensitive Device(ESD)



Package Dimensions (Unit: mm)



Pin Configuration

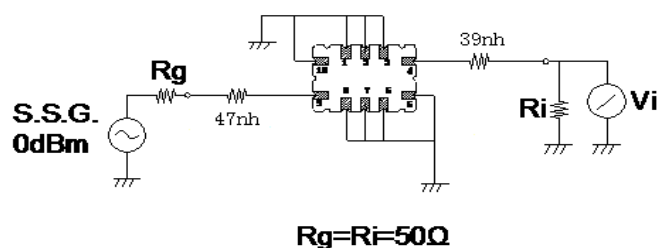
Pin No.	Description
9	Input
4	Output
1,2,3,6,7,8,	Case Ground
5,10	To be Grounded

Marking Description

RF	R	Manufacturer
	F	SAW Filter
2490	Part Number	
●	Pin 1	
YYWW	Year Code & Week Code	

*Fig: If the products produced in 06th week of 2015,
The year code & week code is 1506.

Test Circuit (Bottom View)



Performance**Maximum Rating**

Item		Value	Unit
DC Voltage	V _{DC}	3	V
Operation Temperature	T	-40 ~ +85	°C
Storage Temperature	T _{stg}	-55 ~ +125	°C
RF Power Dissipation	P	15	dBm

Electronic Characteristics

Test Temperature: 25°C ± 2°C

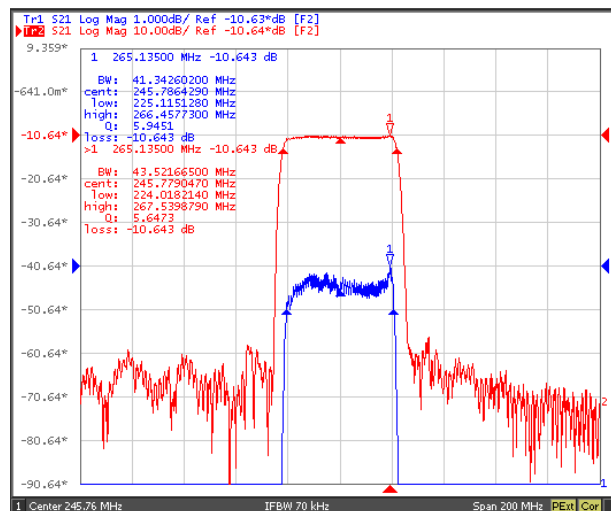
Terminating source impedance: 50Ω

Terminating load impedance: 50Ω

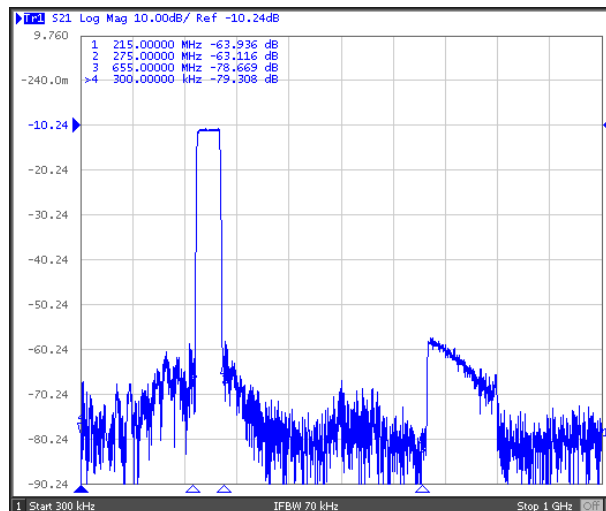
Item		Minimum	Typical	Maximum	Unit
Center Frequency	f _c		245.76		MHz
Insertion Loss(min)	IL		10.6	15.0	dB
Amplitude Ripple	Δα		0.6	1.0	dB
1 dB Bandwidth	BW _{1dB}	38.0	41.0		MHz
3 dB Bandwidth	BW _{3dB}		43.5		MHz
40 dB Bandwidth	BW _{40dB}		50.6	52.0	MHz
Absolute Delay	AD		0.6	3.0	us
Absolute Attenuation	α				
DC – 215.00MHz		45.0	48.0		dB
275.00 – 655.00MHz		40.0	45.0		dB

Frequency Characteristics

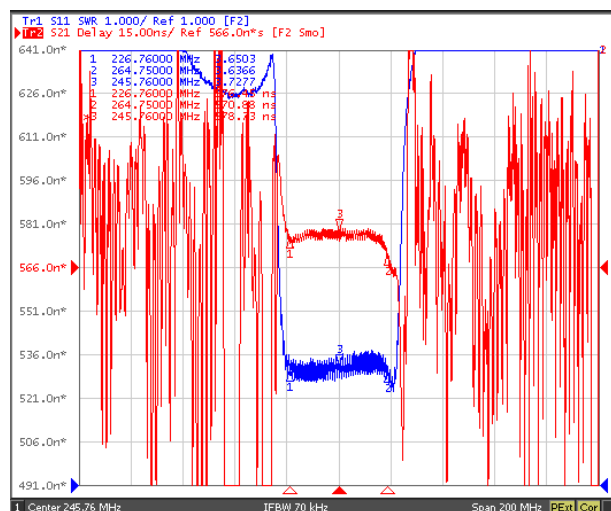
Frequency Response



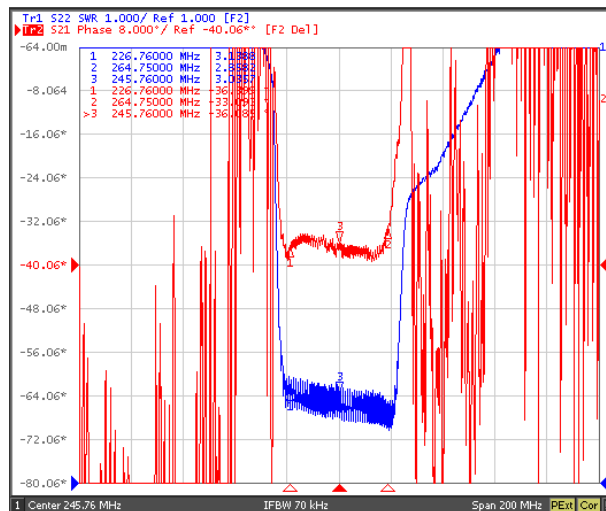
Frequency Response (wideband)



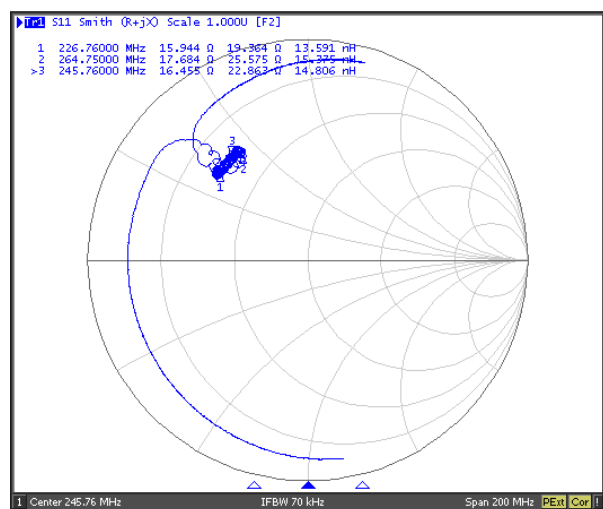
Delay Ripple & S11 VSWR



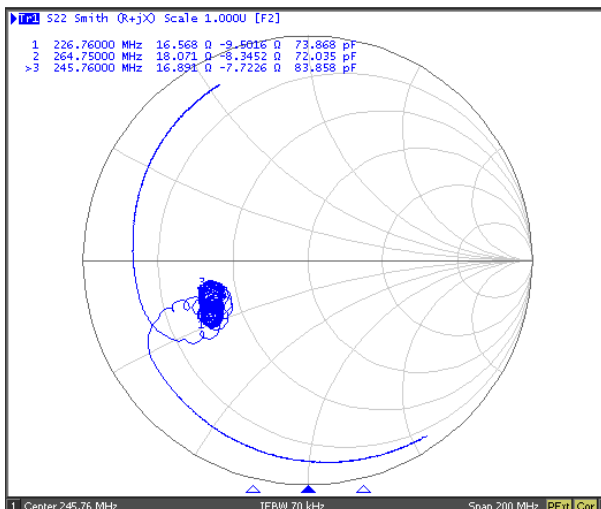
Phase Linearity & S22 VSWR



S11 Smith Chart



S22 Smith Chart



Notes

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.